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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Zou et al.
Serial No.: 10/712,591
Filed: November 13, 2003
For: METHOD OF PROCESSING
SUBSTRATE

Examiner: Unknown
Group Art Unit: Unknown
Docket No.: H0005211 (HON0002/US)

Commissioner for Patents
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The documents listed on the enclosed Form PTO-1449 are presented pursuant to Applicant's duty of disclosure under 37 C.F.R. 1.56. Copies of the articles are enclosed.

No fee is believed to be necessary for the consideration of this Information Disclosure Statement since it is being filed before the receipt of an Office Action on the merits. In case the papers cross in the mail, it is requested that consideration of this Information Disclosure Statement be given under 37 C.F.R. § 1.97 (c)(2). If any fee is required, please charge our Deposit Account No. 50-1775 and notify us of the same.

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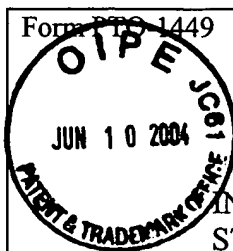
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Form PTO-1449		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. H0005211 (HON0002/US)		Serial No. 10/712,591	
		INFORMATION DISCLOSURE STATEMENT BY APPLICANT					
		Applicant Zou et al.					
		Filing Date November 13, 2003				Group	
U.S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
		4,731,757	03/1988	Daughton et al.			
		4,780,848	10/1988	Daughton et al.			
		5,569,617	10/1996	Yeh et al.			
		5,704,987	01/1998	Huynh et al.			
		5,956,267	09/1999	Hurst et al.			
		6,048,739	04/2000	Hurst et al.			
		6,413,869	07/2002	Achuthan et al.			
		6,500,676	12/2002	Ramberg			
FOREIGN PATENT DOCUMENTS							
	Name	Document Number	Date	Country	Class	Subclass	Translation Yes/No
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
			S. R. Roy et al., "Postchemical-Mechanical Planarization Cleanup Process for Interlayer Dielectric Films," <i>J. Electrochem. Soc.</i> , Vol. 142, No. 1, pp. 216-226, January 1995				
			H. Aoki et al., "A Degradation-Free Cu/HSQ Damascene Technology using Metal Mask Patterning and Post-CMP Cleaning by Electrolytic Ionized Water," <i>IEDM 97</i> , pp. 777-780, 1997				
			M. Kodera et al., "Corrosion Control Technique in Copper Metallization Using Gas Dissolved Water," <i>IEEE</i> , pp. 105-107, 2002				
			N. Miyashita et al., "Characterization of a New Cleaning Method Using Electrolytic Ionized Water for Polysilicon Chemical Mechanical Polishing Process," <i>Jpn. J. Appl. Phys.</i> , Vol. 41, No. 8, pp. 5098-5103, 2002				
			Shirakashi et al., "Technique of surface control with the Electrolyzed D.I. water for post CMP cleaning," Materials Research Society Symposium Proceedings, Volume 612, Symposium held April 23-27, 2000, San Francisco, CA				
			Ali et al., "The Effect of Secondary Platen Downforce on Post-Chemical Mechanical Planarization Cleaning," MICROCONTAMINATION Conference Proceedings, pp. 196-205, 1994				
			D. W. Cooper et al., "Comparing the effectiveness of knobby and ridged post-CMP cleaning brushes," <i>MicroMagazine.com</i> , July 1999				
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